

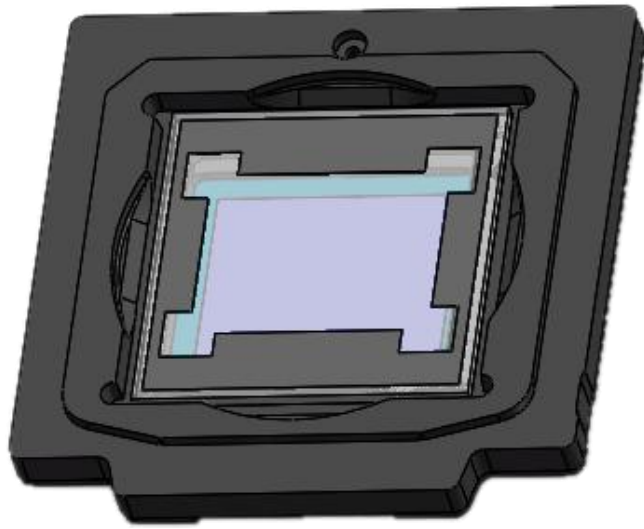
Introduction of COM

- Chip On Module -

(Soldering COB Technology)

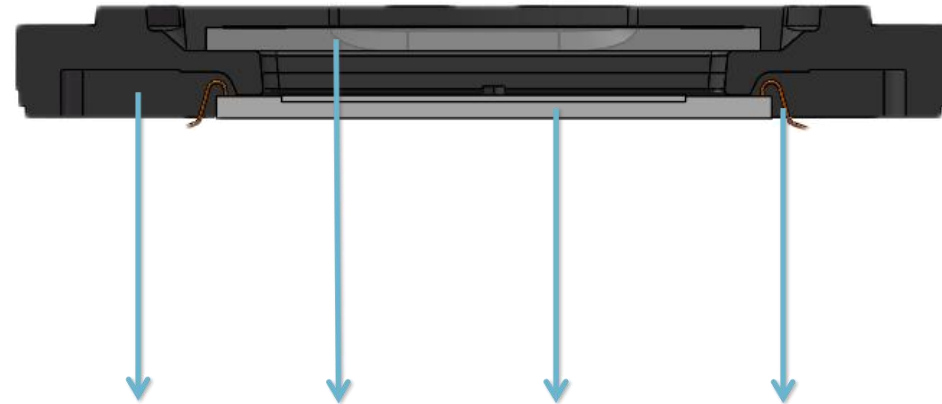
•----- V4.2 -----•

COM Chip

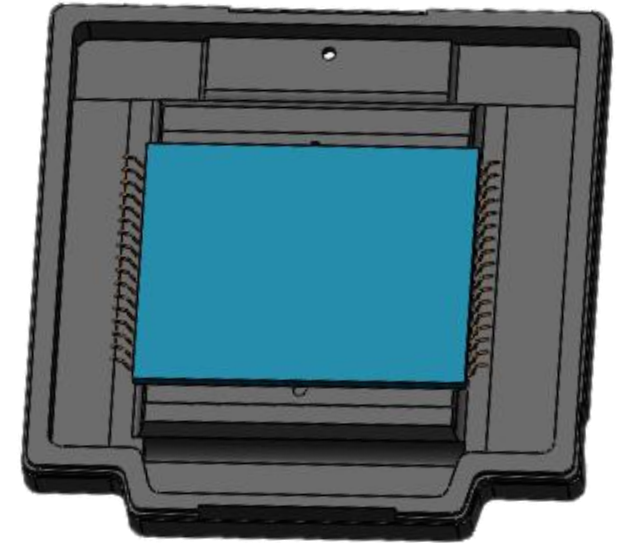


Top View

Side View

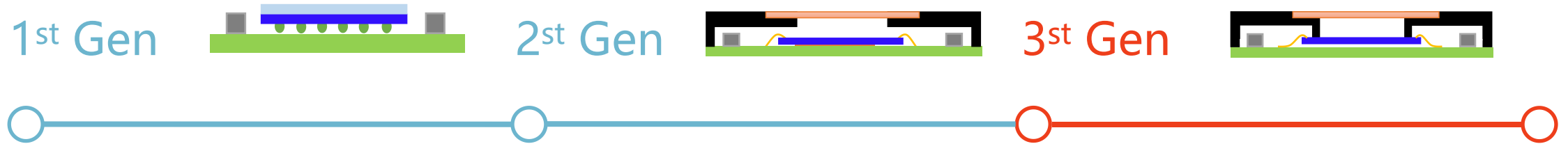


Base IR Glass CIS Die Gold Wire



Bottom View

Soldering COB Technology



CSP Chip Scale Package

- Simple manufacturing process
- Poor optical performance
- Concern of reliability

COB Ultrasonic COB

- Better reliability with gold wire bonding
- Improved optical performance with CSP white glasses removed
- High-cost and complex manufacturing process
- Moving particle issue

COM Soldering COB

- Less moving particle
- Reduced optical tilt error
- Superior reliability of bonding
- Better heat dissipation
- More cost-effective manufacturing
- Need IR glass with mask

COM Roadmap

Series	CIS Model	COM Packaging Size	Status
13M	GC13053	8.5*8.5	Sample
8M	GC8034	8.5*8.5	Ready
5M	GC5035	5.5*4.5 / 6.5*6.5 / 8.5*8.5	Ready
HD	GC1009	5.6*2.8	Ready

- Product roadmap is subject to change without notice
- Please contact Galaxycore representative for details



THANKS
